NEC

MOS FIELD EFFECT TRANSISTOR
NP32N055SLE

SWITCHING
N-CHANNEL POWER MOS FET

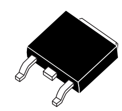
DESCRIPTION

NP32N055SLE is N-channel MOS Field Effect Transistor designed for high current switching applications.

ORDERING INFORMATION

PART NUMBER	PACKAGE
NP32N055SLE	TO-252 (MP-3ZK)

(TO-252)



FEATURES

- Channel temperature 175 degree rating
- Super low on-state resistance
  $R_{DS(on)1}$ = 24 mΩ MAX. (V_{GS} = 10 V, I_D = 16 A)
  $R_{DS(on)2}$ = 29 mΩ MAX. (V_{GS} = 5.0 V, I_D = 16 A)
- Low C_{iss} : C_{iss} = 1300 pF TYP.
- Built-in gate protection diode

ABSOLUTE MAXIMUM RATINGS (T_A = 25°C)

Drain to Source Voltage (V_{GS} = 0 V)	V_{DSS}	55	V
Gate to Source Voltage (V_{DS} = 0 V)	V_{GSS}	±20	V
Drain Current (DC) (T_C = 25°C)	$I_{D(DC)}$	±32	A
Drain Current (pulse) Note1	$I_{D(pulse)}$	±100	A
Total Power Dissipation (T_C = 25°C)	P_T	66	W
Total Power Dissipation (T_A = 25°C)	P_T	1.2	W
Channel Temperature	T_{ch}	175	°C
Storage Temperature	T_{stg}	–55 to +175	°C
Single Avalanche Current Note2	I_{AS}	28/21/8	A
Single Avalanche Energy Note2	E_{AS}	7.8/44/64	mJ

Notes 1. PW ≤ 10 μs, Duty Cycle ≤ 1%

2. Starting T_{ch} = 25°C, R_G = 25 Ω , V_{GS} = 20 → 0 V (See Figure 4.)

THERMAL RESISTANCE

Channel to Case Thermal Resistance	$R_{th(ch-C)}$	2.27	°C/W
Channel to Ambient Thermal Resistance	$R_{th(ch-A)}$	125	°C/W

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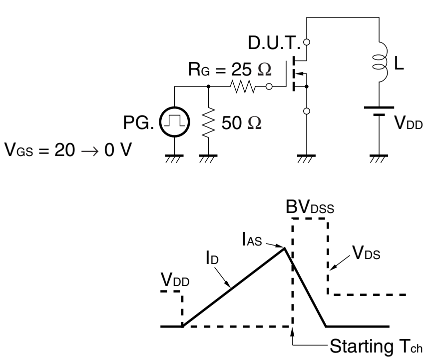
ELECTRICAL CHARACTERISTICS (T_A = 25°C)

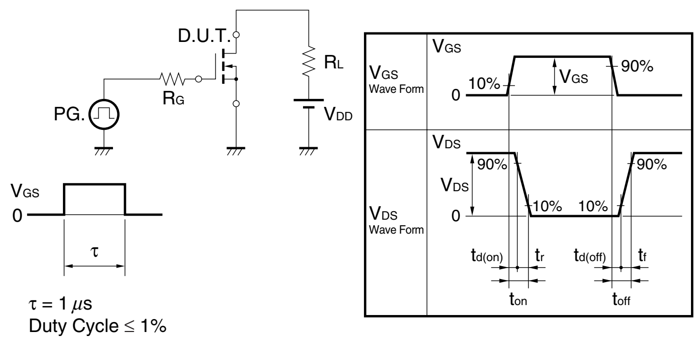
CHARACTERISTICS	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Zero Gate Voltage Drain Current	I_{DSS}	V_{DS} = 55 V, V_{GS} = 0 V			10	μA
Gate Leakage Current	I_{GSS}	V_{GS} = ±20 V, V_{DS} = 0 V			±10	μA
Gate to Source Threshold Voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250 μA	1.5	2	2.5	V
Forward Transfer Admittance Note	$\mid y_{fs} \mid$	V_{DS} = 10 V, I_D = 16 A	8	16		S
Drain to Source On-state Resistance Note	$R_{DS(on)1}$	V_{GS} = 10 V, I_D = 16 A		19	24	mΩ
	$R_{DS(on)2}$	V_{GS} = 5.0 V, I_D = 16 A		22	29	mΩ
	$R_{DS(on)3}$	V_{GS} = 4.5 V, I_D = 16 A		24	33	mΩ
Input Capacitance	C_{iss}	V_{DS} = 25 V		1300	2000	pF
Output Capacitance	C_{oss}	V_{GS} = 0 V		180	270	pF
Reverse Transfer Capacitance	C_{rss}	f = 1 MHz		90	160	pF
Turn-on Delay Time	$t_{d(on)}$	V_{DD} = 28 V, I_D = 16 A		14	31	ns
Rise Time	t_r	V_{GS} = 10 V		8	20	ns
Turn-off Delay Time	$t_{d(off)}$	R_G = 1 Ω		40	81	ns
Fall Time	t_f			7.4	19	ns
Total Gate Charge	Q_{G1}	I_D = 32 A, V_{DD} = 44 V, V_{GS} = 10 V		27	41	nC
	Q_{G2}	V_{DD} = 44 V		15	23	nC
Gate to Source Charge	Q_{GS}	V_{GS} = 5.0 V		5		nC
Gate to Drain Charge	Q_{GD}	I_D = 32 A		9		nC
Body Diode Forward Voltage Note	$V_{F(S-D)}$	I_F = 32 A, V_{GS} = 0 V		1.0		V
Reverse Recovery Time	t_{rr}	I_F = 32 A, V_{GS} = 0 V		41		ns
Reverse Recovery Charge	Q_{rr}	di/dt = 100 A/μs		58		nC

Note Pulsed

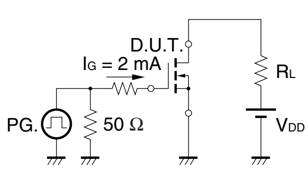
TEST CIRCUIT 1 AVALANCHE CAPABILITY



TEST CIRCUIT 2 SWITCHING TIME



TEST CIRCUIT 3 GATE CHARGE



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TYPICAL CHARACTERISTICS (T_A = 25°C)

Figure1. DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA

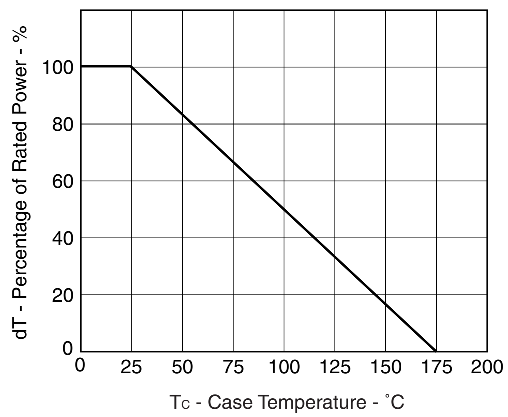

Figure2. TOTAL POWER DISSIPATION vs. CASE TEMPERATURE

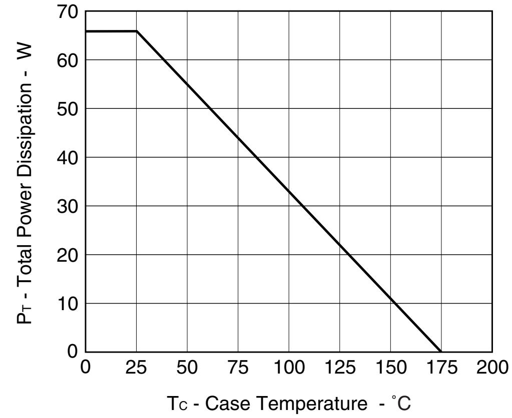

Figure3. FORWARD BIAS SAFE OPERATING AREA

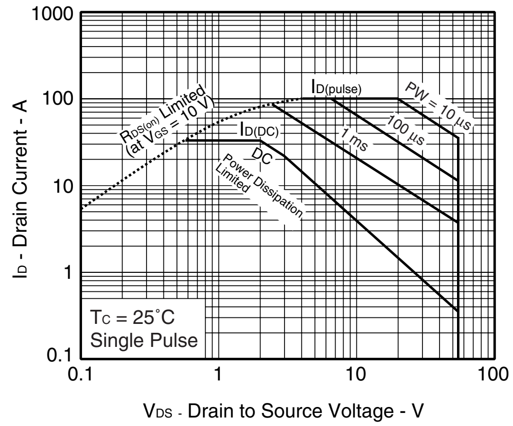

Figure4. SINGLE AVALANCHE ENERGY DERATING FACTOR

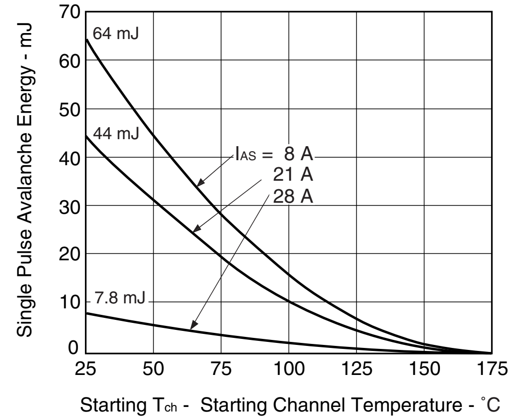

Figure5. TRANSIENT THERMAL RESISTANCE vs. PULSE WIDTH

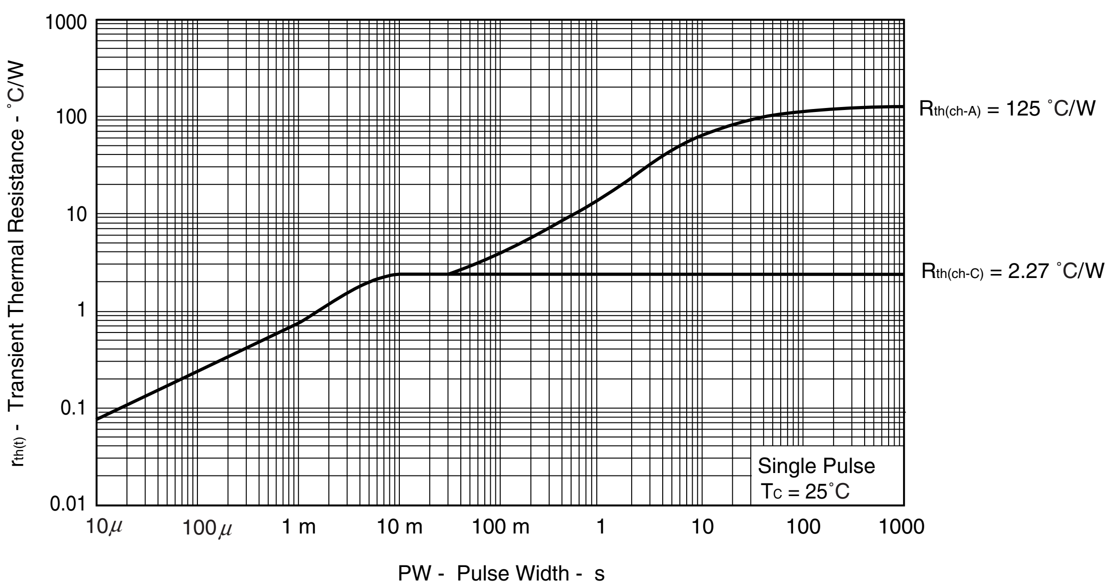

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Figure6. FORWARD TRANSFER CHARACTERISTICS

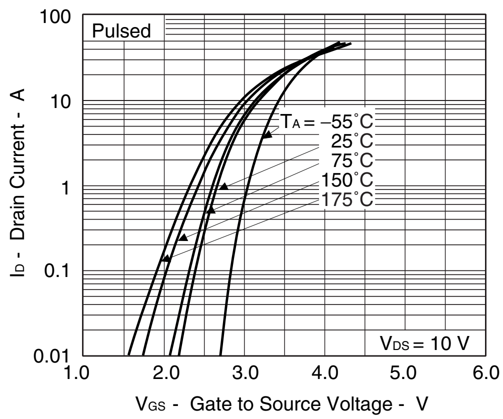

Figure7. DRAIN CURRENT vs. DRAIN TO SOURCE VOLTAGE

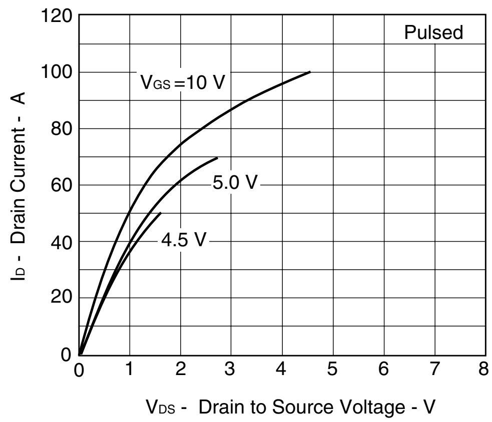

Figure8. FORWARD TRANSFER ADMITTANCE vs. DRAIN CURRENT

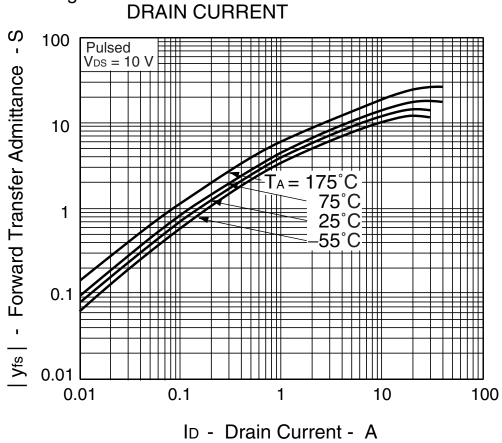

Figure9. DRAIN TO SOURCE ON-STATE RESISTANCE vs. GATE TO SOURCE VOLTAGE

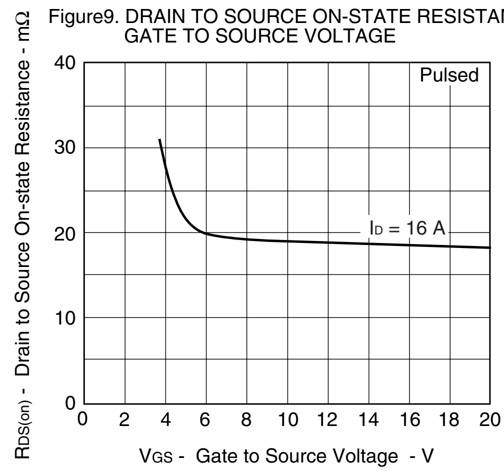

Figure10. DRAIN TO SOURCE ON-STATE RESISTANCE vs. DRAIN CURRENT

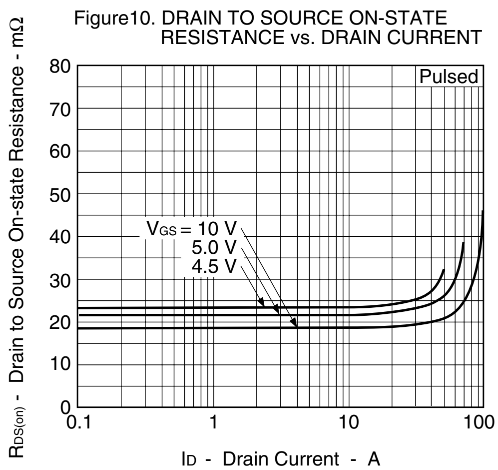

Figure11. GATE TO SOURCE THRESHOLD VOLTAGE vs. CHANNEL TEMPERATURE

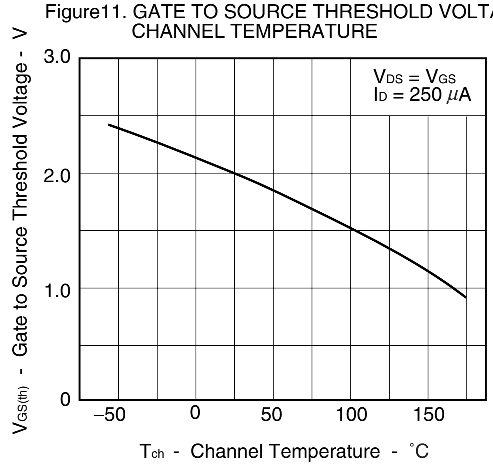

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Figure12. DRAIN TO SOURCE ON-STATE RESISTANCE vs. CHANNEL TEMPERATURE

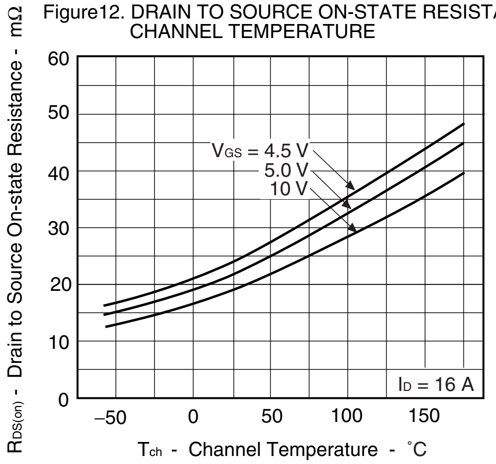


Figure13. SOURCE TO DRAIN DIODE FORWARD VOLTAGE

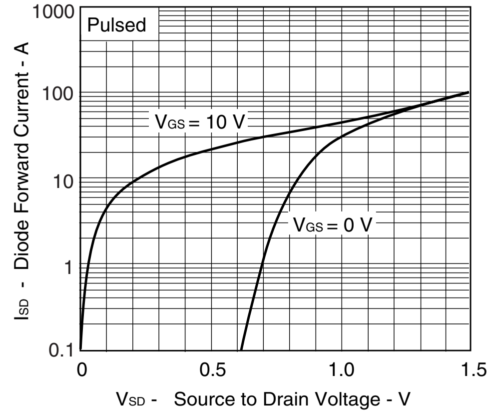


Figure14. CAPACITANCE vs. DRAIN TO SOURCE VOLTAGE

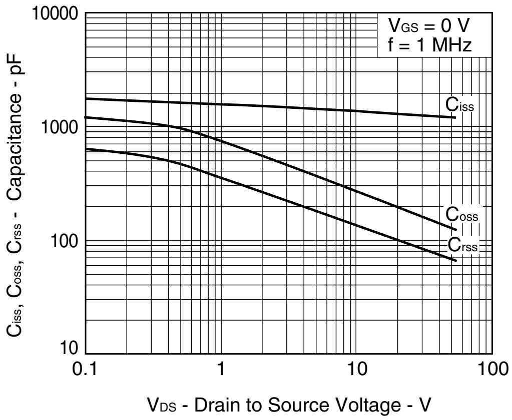


Figure15. SWITCHING CHARACTERISTICS

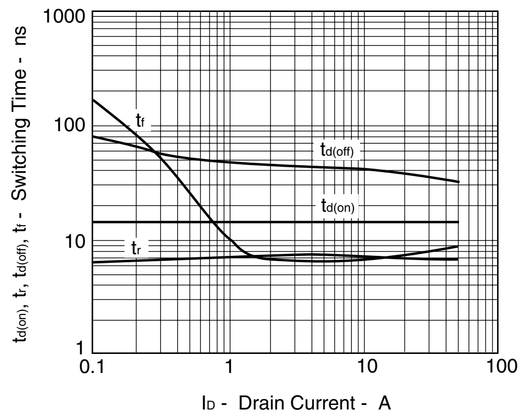


Figure16. REVERSE RECOVERY TIME vs. DRAIN CURRENT

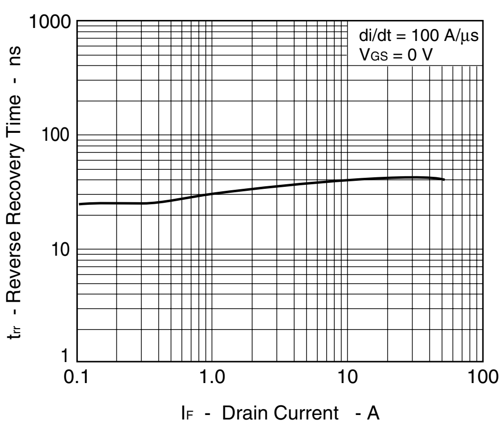
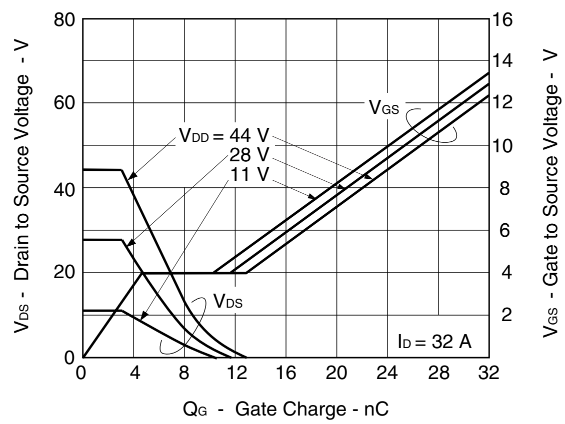


Figure17. DYNAMIC INPUT/OUTPUT CHARACTERISTICS



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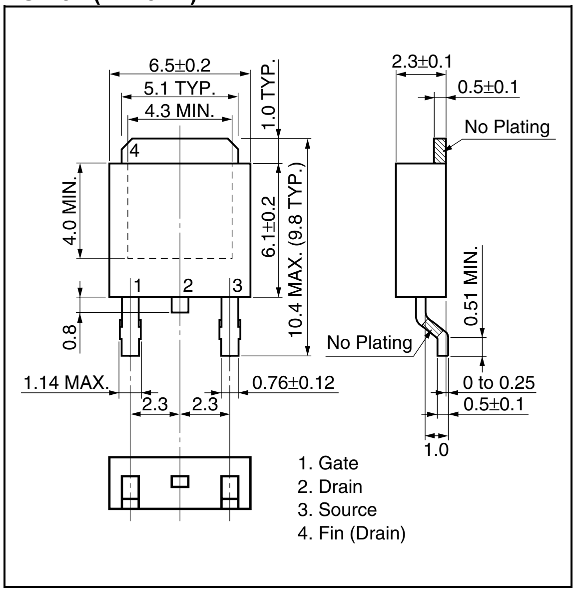
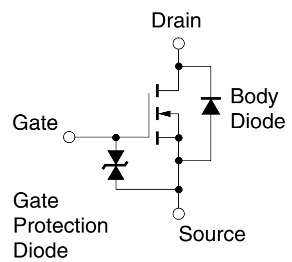
PACKAGE DRAWING (Unit: mm)

TO-252 (MP-3ZK)



EQUIVALENT CIRCUIT



Remark The diode connected between the gate and source of the transistor serves as a protector against ESD. When this device actually used, an additional protection circuit is externally required if a voltage exceeding the rated voltage may be applied to this device.

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